

Amended Claims With Mark-ups to Show Changes Made

Sub:
C1
13. (Amended) A method for surface mounting electrical components on a printed circuit board (PCB) with a surface mounter, comprising:

locating a PCB at a first mounting position by moving the PCB in both the X and Y directions within a working area of the surface mounter;

picking up a plurality of electrical components with a corresponding plurality of suction nozzles; and

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moving the plurality of suction nozzles simultaneously to substantially simultaneously mount [the] a plurality of electrical components on the PCB.

32. (Amended) The method of claim 28, wherein the moving step comprises simultaneously moving the plurality of mounter heads to mount the electrical components [of] on the PCB.
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Clean Set of Amended Claims

13. (Amended) A method for surface mounting electrical components on a printed circuit board (PCB) with a surface mounter, comprising:

locating a PCB at a first mounting position by moving the PCB in both the X and Y directions within a working area of the surface mounter;

picking up a plurality of electrical components with a corresponding plurality of suction nozzles; and

moving the plurality of suction nozzles simultaneously to substantially simultaneously mount a plurality of electrical components on the PCB.

32. (Amended) The method of claim 28, wherein the moving step comprises simultaneously moving the plurality of mounter heads to mount the electrical components on the PCB.